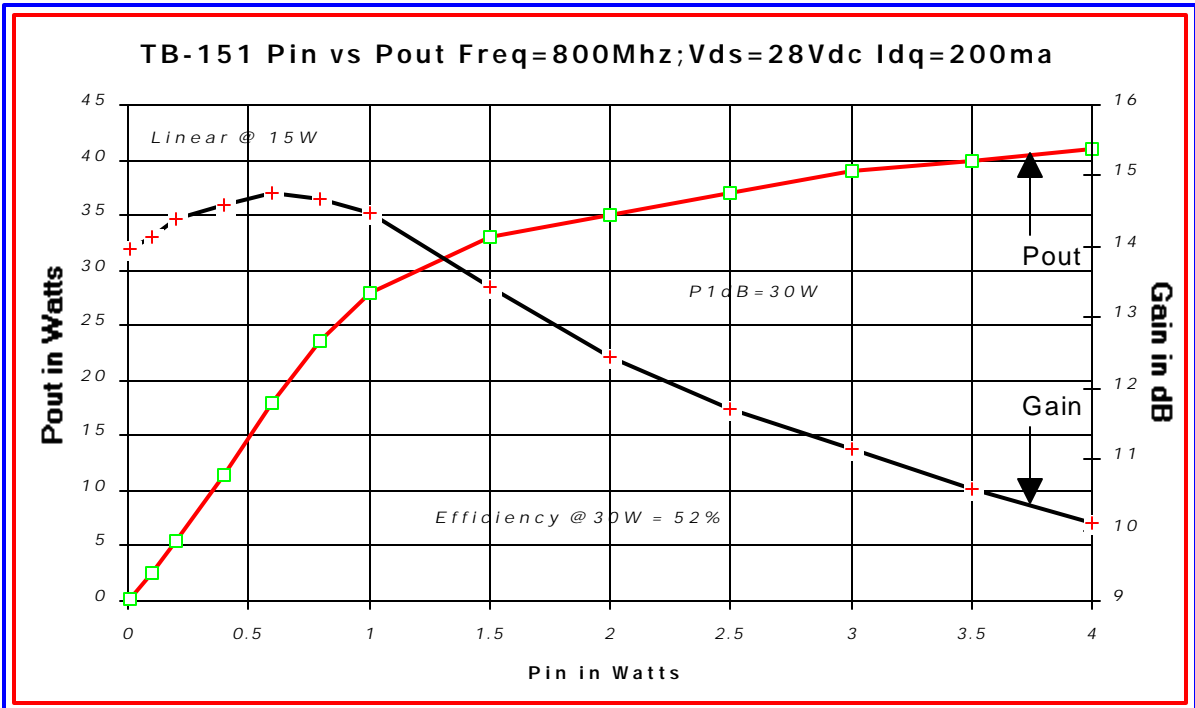
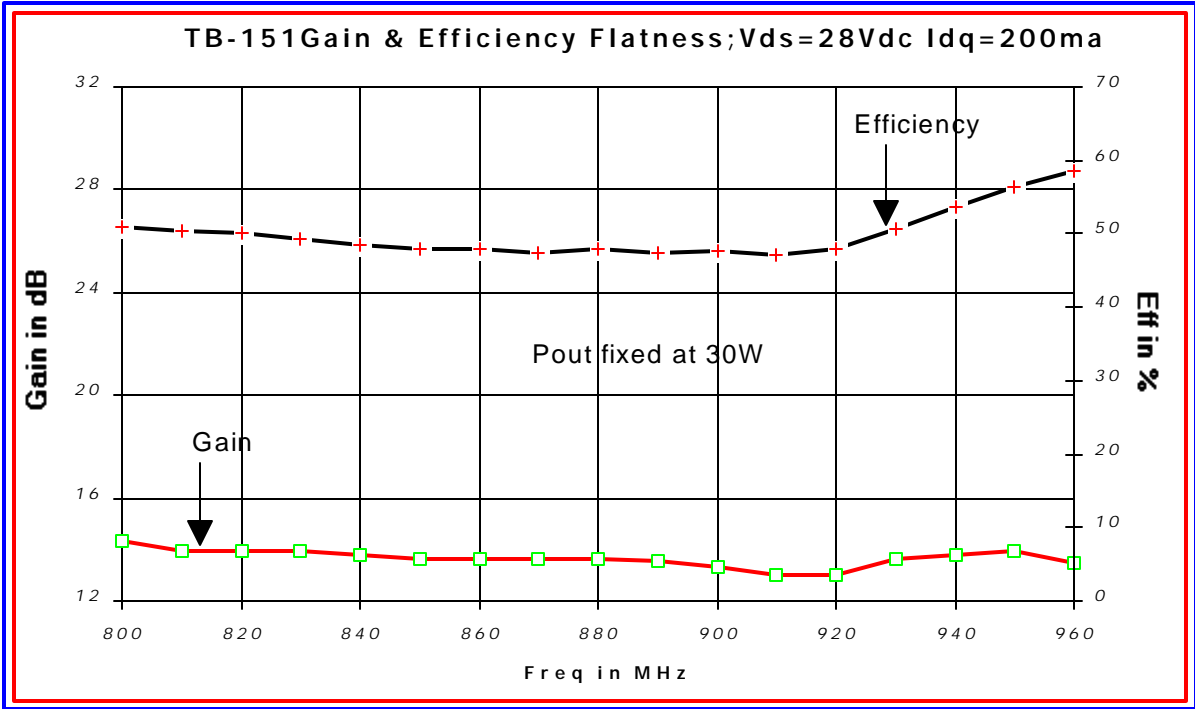
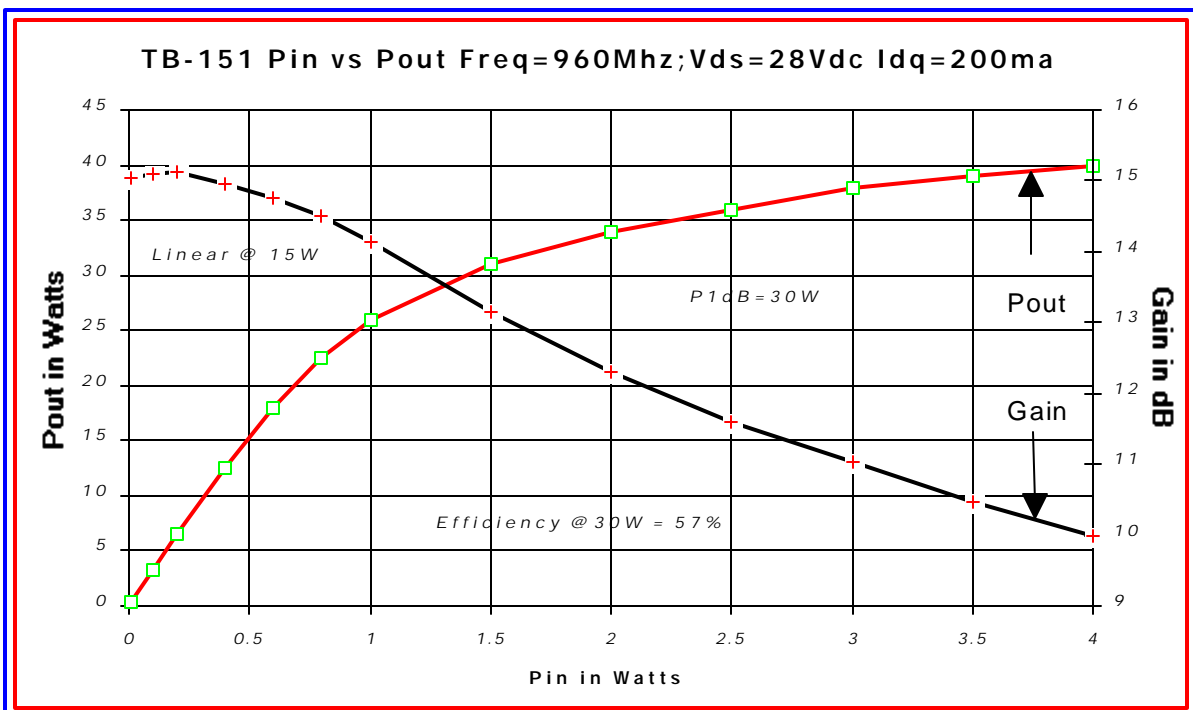
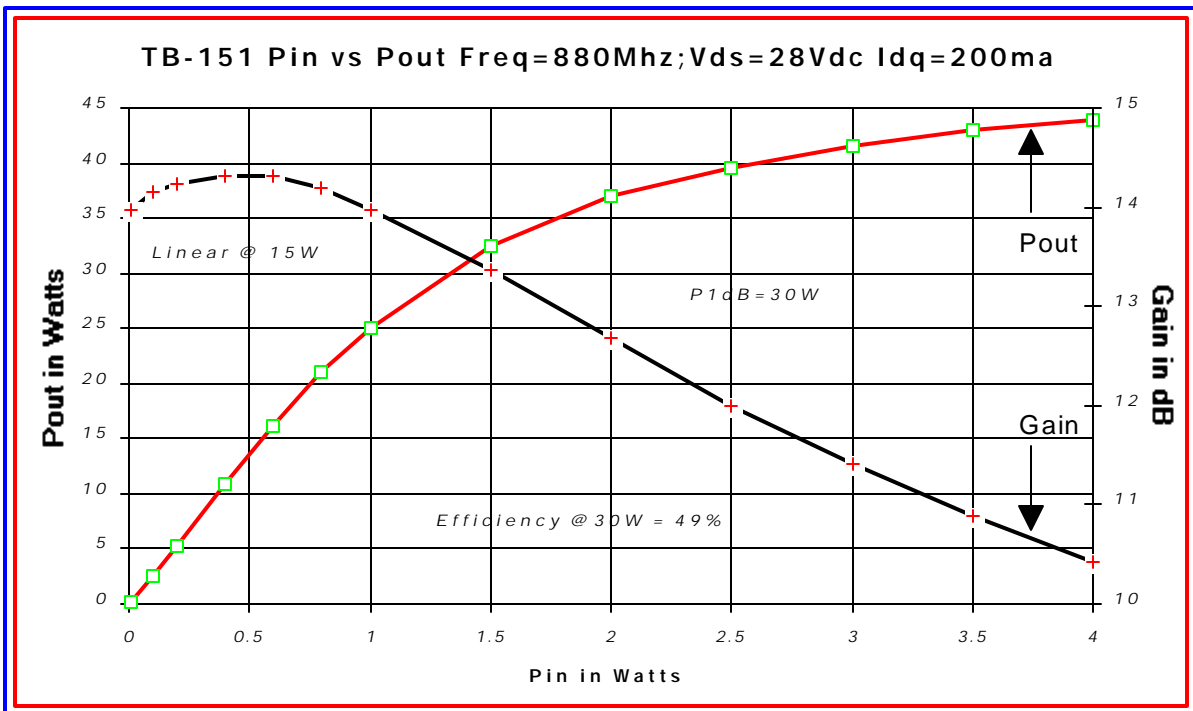


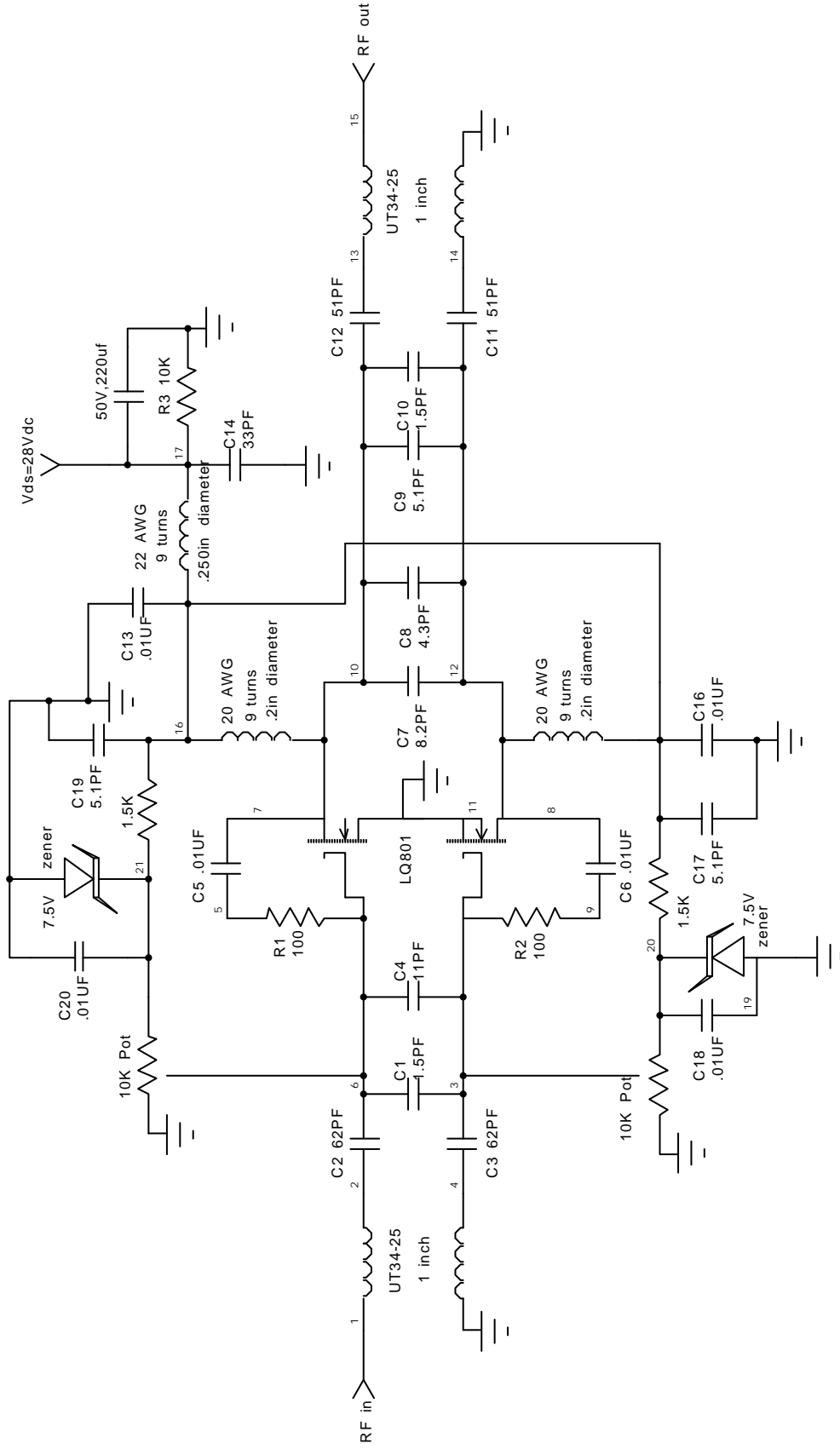
PCB Material : Double Side Teflon
 ER=2.5, H=32, T=1.4

SYMBOL	VALUE	DESCRIPTION
C01, C02	62pf	ATC-1008 Chip Cap.
C03	15pf	ATC-1008 Chip Cap.
C04	11pf	ATC-1008 Chip Cap.
C05	82pf	ATC-1008 Chip Cap.
C06	15pf	ATC-1008 Chip Cap.
C07, C08	51pf	ATC-1008 Chip Cap.
C09, 11, 14, 16	.01uf	ATC-1008 Chip Cap.
C10, C12	51pf	ATC-1008 Chip Cap.
C13	51pf	ATC-1008 Chip Cap.
C15	4.3pf	ATC-1008 Chip Cap.
C18	33pf	ATC-1008 Chip Cap.
L01, L02	---	#80AVG 8 Turn
L03	---	#180MG 4T Vound
V01	---	#18AVG Wire Bridge
T01, T02	1500mH	UT34-25 Coorxkl
R01, R02	1.5k	1206 CHD Res.
P01, P02	10k	6x6mm Potentiometer
D01, D02	6.8V	Zener
VDD	28V	DC Power Supply
B05	400mA	B05 Current

DRN BY: ZHU JN	28/10/99	POLYFET RF DEVICES	
CHKD :		SIZE	TB-151 850-910MHZ
ELECT :		PCB NO	PCB LAYOUT
MECH :		REV	2
PRJ :		SCALE	1 : 1
QML :		SHEET	1 OF 2
PGMS :			







DRN :	J Citrolo	10/26/00
CHK :	E. Greenbaum	10/26/00
ELECT :		
MECH :	K. S. Tay	10/26/00
PROC :		
QUAL :		
PGMS :		

Polyfet RF Devices

850 - 910MHZ, 30W, 28V

Size	FSCM NO	Rev
TB 151		.
Scale	Sheet 1 of 1	